

1) Introductions and Roster modifications

2) May 2009 meeting minutes approval

2 Old business

3 New business

3.1 Revision to IPC/EIA J-STD-002

3.1.1 Alignment of J-STD-002 and JEDEC B102

Latest Status:

- Dave Hillman has summarized differences between JSTD-002/B102.
- Paul Melville has provided a summary of JEDEC JC14.1 inputs on JSTD-002.
- Hillman, Melville, and Romm have had conference calls to review DOE status and align message for industry standards committees.
- Input from Mr. Melville is "The JEDEC position remains that JESD22-B102 will be rescinded and replaced by J-STD-002 after these issues are resolved."

3.2 Possible replacements for steam pre-conditioning

Status of the DOE will be discussed.

- Data collection for DOE is complete.
- Two facilities performed Wetting Balance (RIM, Bev Christian, STS, Gerard O'Brien)
- One facility to perform assembly processing (Rockwell-Collins, Hillman)
- Assembly processing is pending.
- Data is being reviewed at Fall meetings of IPC (Sept 21st Fall) and STC (Fall)
- Assembly processed units will be judged for visual wetting per J-STD-002; flux is ROL0 rosin based no activation, most conservative.
- Intent would be to use the assembly data to scale where we need to be on the solderability test.
- Confirmation run is needed.

3.3 Gauge R&R for wetting balance test

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. Team needs to discuss plans/timing for future work.

4 Next meeting

5 Adjournment